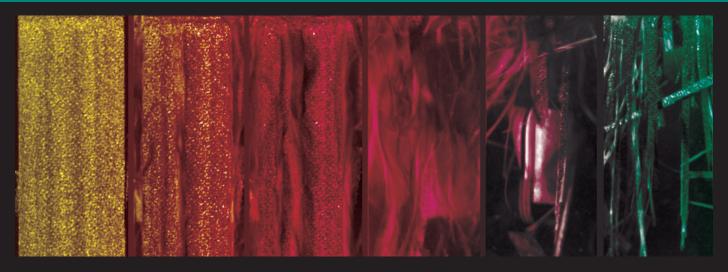
Call for abstracts



High speed imaging for dynamic testing of materials and structures 21st DYMAT Technical Meeting

18-20 November 2013, Institute of Physics, London, UK

Organised jointly by the IOP Applied Physics and Technology Division and DYMAT Association



http://aptd.iopconfs.org

Main conference themes

- Metrology
 - Camera/equipment assessment
 - DIC, grids, etc: metrological evaluation for full-field strain and acceleration measurements
 - High and ultra high speed full-field thermal measurements
- Methodology
 - Full-field measurements data processing
 - Parameter identification/inverse problems
 - Innovative test design
- Applications
 - Constitutive behaviour
 - Failure/fracture
 - Observation of damage and failure processes
 - All types of materials/structures will be considered

Keynote speakers

- Prof. John E Field, University of Cambridge, UK
- Dr Phillip Reu, Sandia National Laboratories, USA
- Prof. Mikael Sjödahl, Luleå University of Technology, Sweden

Format

The meeting will take place over three days in single-session format to maximise interaction between speakers and audience. The conference will also include interactive poster sessions, an exhibition of high-speed camera manufacturers and a round-table session on current challenges and future developments in high-speed imaging.

Publication

Four-page abstracts for oral and poster presentations are invited. In parallel, some authors will be asked to contribute to a themed issue on the meeting topic, to be published in *Strain* (Wiley-Blackwell).

Important deadlines

Extended abstract submission deadline	14 June 2013
Early registration deadline	31 July 2013
Registration deadline	11 November 2013

Organising committee

- Prof. Fabrice Pierron, University of Southampton, UK
- Prof. Janice M Barton, University of Southampton, UK
- Prof. Pascal Forquin, Lorraine University, France
- Dr Alec Goodyear, The Open University, UK
- Prof. William G Proud, Imperial College London, UK
- Dr Clive Siviour, University of Oxford, UK

Co-sponsors

British Society for Strain Measurement (BSSM); European Physical Society; the Imaging Science Group, Royal Photographic Society; Institute of Measurement and Control; Institution of Mechanical Engineers; Society for Experimental Mechanics, Inc (SEM)

Further information

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